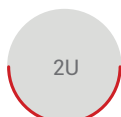


GAP-245PL - G6 Series

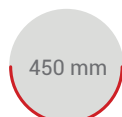
2U RUGGED SERVER



Intel® Xeon® Scalable Processors
Front I/O - Front Power Supply



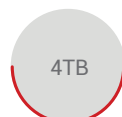
Platform



Depth



CPU



RAM



SSD



I/O Boards

GAP is a line of rugged servers and workstations with an aluminum construction, designed for applications that require robust and qualified MIL-GRADE equipment, suitable for operating in critical environments.

GAP-245PL G6 rugged servers feature single or dual socket Intel® Xeon® Scalable Processors (Skylake-SP / Cascade Lake-SP) supporting up to 28 cores and 56 thread, up to 38.5 MB cache, Intel® Ultra Path Interconnect, Intel® AVX-512, up to six memory channels and up to 48 PCIe 3.0 lanes. The integrated IPMI services support monitoring, control, and management functions sending alarm notifications in case of critical events.

GAP-245RL are designed for 19" rackmounting and have 2U chassis with 450mm depth.

The front I/O and power supply input layout includes up to three removable SSD and an optional slim DVD.

GAP-245PL rugged servers can host six low profile PCIe cards.

GAP servers are designed to meet according to MIL-STD-810F for temperature and shocks, MIL-STD-167-1A for vibrations and can optionally conform to MIL-STD-461 for EMI /EMC.

Upon request the I/O connectors and the power supply input can be provided with MIL-GRADE connectors.

All units are delivered with their inventory list to ensure configuration control and reproducibility over time. Upon request, all server configurations can run specific thermal or mechanical environmental stress test.

FEATURES

- 2U Rugged Server - 450mm depth
- Single or Dual Processor
- Intel Xeon® Scalable Processors (I and II Gen)
- Front I/O connectors
- Front Power Input
- Redundant AC or DC Power Supply
- Up to 3 SSD Hot Swap (Max 2 x NVME)
- Optional DVD
- Up to 6 Low Profile boards
- Optional Conformal Coating
- MIL-STD-810G
- Optional MIL-STD-461

Technical Specifications

System

Processor	Intel® Xeon® Scalable Processors Family (up to 250W TDP) - Dual Socket P (LGA 3647) - Up to 28 cores
Memory	Up to 4TB ECC RDIMM, DDR4- 2933/2666/2400/2133MHz – 16 DIMM slot
Chipset	Intel® C621
Network	2 x RJ45 Gigabit Ethernet
Storage	2.5" SATA Disk - RAID 0, 1, 5, 10 PCIe 3.0 NVMe x4 Internal Port M.2 Interface: PCI-E 3.0 x4 - 2260, 2280, 22110 M.2 Key: M-Key
TPM	1 TPM Header
Motherboard I/O	Available on the front: 1 x VGA, 2 x USB 2.0, 2 x USB 3.0, 2 x GbE, 1 x IPMI LAN, 1 x COM
Expansion slots	Up to 6 x PCIe Low profile
Operative Systems	Windows® 8.1, Windows® 10 IoT Enterprise 2016, Windows® Server 2012 R2, Windows® Server 2016, Windows® Server 2019, Linux, Vmware, Xen Server
IPMI	IPMI2.0, SPM, Watchdog; SNMP and e-mail alarms and notifications
Monitoring	Monitoring, control, and management functions (fan speed, temperature, voltage, redundant power failure, power consumption, disk health, raid health, and memory health)

Power Supply

Power Supply	100/240 Redundant VAC 18-36 Single or Redundant VDC 36-72 Single or Redundant VDC
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Mechanical

Dimensions	483 x 88 x 450 mm
Construction	Aluminum with surface passivation treatment
Colour	Silver
Mounting	2U 19" rackmount chassis Telescopic slides optional
Configuration	Front I/O and Power Supply
Front Panel	Led: Led Power ON and HDD/SSD functionality; Switch: Power ON / OFF and System Reset
Drive Bay	1 x slim 5.25" ; 1 x 3.5" bay

Environmental - (Design to meet)

Operative Temperature	Standard: 0°C / +50°C Extended: -20°C / +60°C (depending on the configurations)
Operative Humidity	8% to 95% non-condensed (depending on the configurations)
Storage Temperature	-40°C / +70°C
Vibrations	MIL-STD-810G, Method 514.7, Cat 4 - Proc. I - 2.24 Grms, 5-500 Hz 60 min/axis for 3 axes
Operative Shock	MIL-STD-810G Proc. I Method 516.7 - 15g / 11ms – half sine
Transport shock	MIL-STD-810G Proc. II Method 516.7 - 30g / 9ms sawtooth
Certifications	Directive 2014/35/UE-LVD / Directive 2014/30/UE-EMC Directive 2011/65/UE - RoHS / Regulation (EC) No 1907/2006 - REACH

GAP servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.